

# YETDA INDUSTRY LTD.

# **Technical Data Sheet**

# MODEL NO: S170ANB4-GF

0805Package 2.0\*1.2mm Chip LEDs

### Features :

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

## Applications :

#### Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

## Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test	Symbol	Value			l lm¦t	
	Condition		Min	Тур	Max	Unit	
Dominant wavelength	IF=20mA	λD	В		470		nm
Forward voltage	IF=20mA	VF	В	2.6		3.6	V
Luminous intensity	IF=20mA	lv	В	20		72	mcd
Viewing angle at 50% lv	IF=10mA	2 <i> </i>	В		120		Deg
Reverse current	Vr=5V	Ir	В			10	μA

### Absolute Maximum Ratings(Ta=25°C)

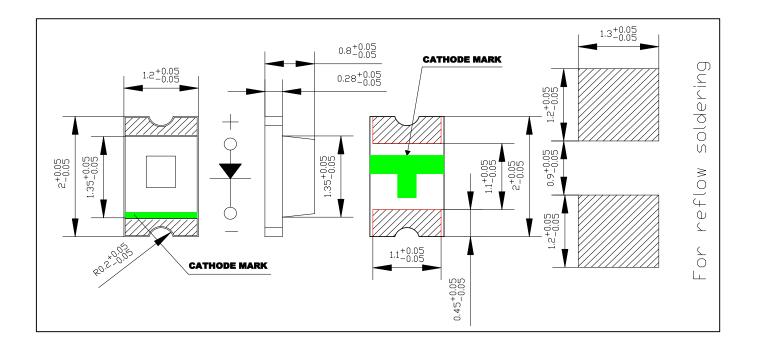
Parameter	Symbol	Value	Unit
Power dissipation	Pd	90	mW
Forward current	lf	20	mA
Reverse voltage	VR	8	V



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Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	<b>I</b> FP	100	mA

# PACKAGING DIMENSIONS (mm):





## **Precautions For Use :**

### **Over - current - proof**

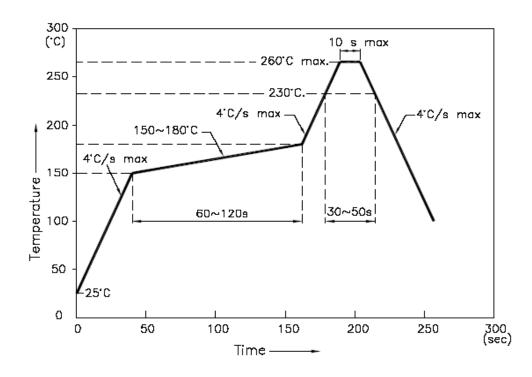
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### Storage

1. The operation of temperature and R.H. are  $: 5^{\circ}$ C  $\sim 30^{\circ}$ C,  $60^{\circ}$ R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : 60°C±5°C for 15hrs.

## ■ Reflow Temp/Time



### NOTES:

- 1. We recommend the reflow temperature  $245^{\circ}C(\pm 5^{\circ}C)$ .the maximum soldering temperature should be limited to  $260^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.



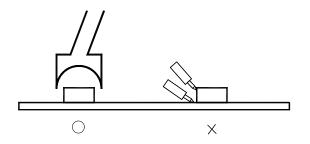
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### ■Soldering iron

Basic spec is  $\leq 5$ sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

### Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 
solder etc.